molex
one company > a world of innovation

This document was generated on 02/29/2016

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:	**0736590004**
Status:	**Active**
Overview:	HDM® Backplane Connector System
Description:	HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm

Documents:

3D Model	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

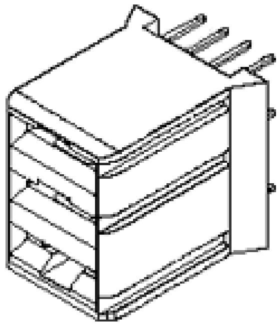
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73659
Application	Backplane
Comments	Midplane Power Module
Component Type	Power Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800755024852

Physical

Circuits (Loaded)	12
Circuits (maximum)	12
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	1.609/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	3.810µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant

REACH SVHC
Not Contained Per -ED/79/2015 (17 December 2015)

Halogen-Free Status
Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the Contact Us section for any non-product compliance questions.

China ROHS	Green Image
ELV	Not Relevant

Search Parts in this Series
73659 Series

Mates With
73651 HDM® Board-to-Board Daughterboard Power Module

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	REFLOW
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Sales Drawing	SDA-73659-000*

Note: HDM, HDM+, VHDM, VHDM-HSD and GbX are trademarks or registered trademarks of Amphenol TCS.

This document was generated on 02/29/2016

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION